

SN54AS821A, SN74AS821A 10-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SDAS230A – DECEMBER 1983 – REVISED AUGUST 1995

- Functionally Equivalent to AMD's AM29821
- Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Outputs Have Undershoot-Protection Circuitry
- Power-Up High-Impedance State
- Buffered Control Inputs to Reduce dc Loading Effects
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

description

These 10-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

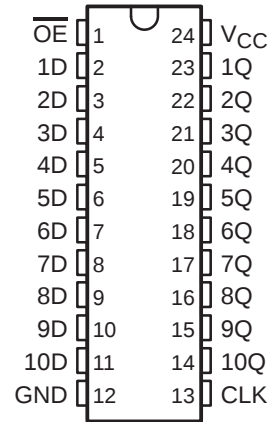
The ten flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are true to the data (D) input.

A buffered output-enable ($\overline{OE}$) input can be used to place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

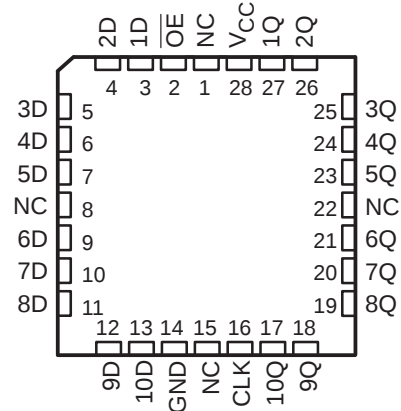
$\overline{OE}$ does not affect the internal operation of the flip-flops. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54AS821A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74AS821A is characterized for operation from 0°C to 70°C .

SN54AS821A . . . JT PACKAGE
SN74AS821A . . . DW OR NT PACKAGE
(TOP VIEW)



SN54AS821A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT Q
$\overline{OE}$	CLK	D	
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	L	X	Q_0
H	X	X	Z

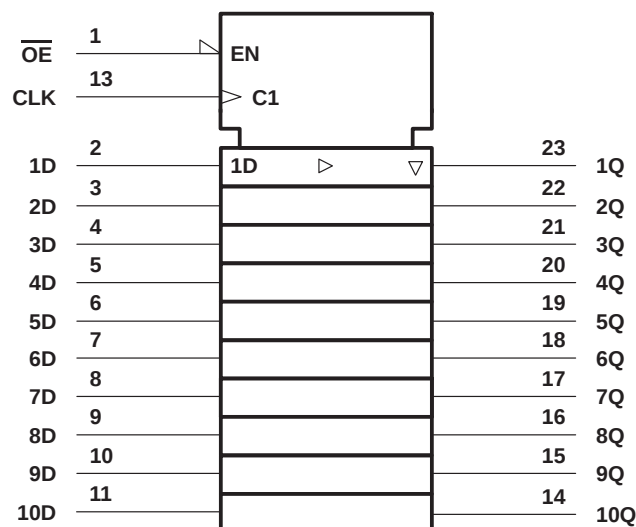
SN54AS821A, SN74AS821A

10-BIT BUS-INTERFACE FLIP-FLOPS

WITH 3-STATE OUTPUTS

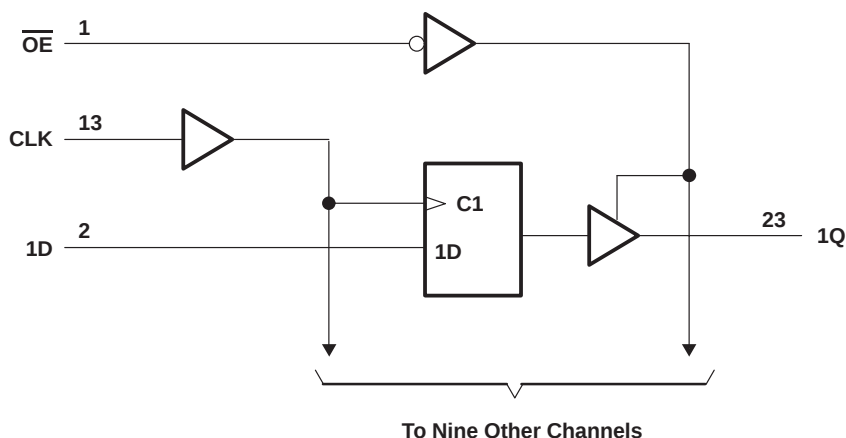
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T_A : SN54AS821A	–55°C to 125°C
SN74AS821A	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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SDAS230A – DECEMBER 1983 – REVISED AUGUST 1995

recommended operating conditions

		SN54AS821A			SN74AS821A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			32			48	mA
t_w^*	Pulse duration, CLK high or low	9			8			ns
t_{su}^*	Setup time, data before CLK $\uparrow$	7			6			ns
t_h^*	Hold time, data after CLK $\uparrow$	0			0			ns
T_A	Operating free-air temperature	–55		125	0		70	°C

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54AS821A			SN74AS821A			UNIT
			MIN	TYP †	MAX	MIN	TYP †	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$				–1.2			–1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -2\text{ mA}$		$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -15\text{ mA}$		2.4	3.2		2.4	3.2		
	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -24\text{ mA}$		2			2			
V_{OL}	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 32\text{ mA}$			0.25	0.5				V
	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 48\text{ mA}$					0.35	0.5		
I_{OZH}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$				50			50	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$				–50			–50	μA
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$				0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$				20			20	μA
I_{IL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$				–0.5			–0.5	mA
$I_{O^\ddagger}$	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$		–30		–112	–30		–112	mA
I_{CC}	$V_{CC} = 5.5\text{ V}$	Outputs high		55	88		55	88	mA
		Outputs low		68	109		68	109	
		Outputs disabled		70	113		70	113	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

SN54AS821A, SN74AS821A

10-BIT BUS-INTERFACE FLIP-FLOPS

WITH 3-STATE OUTPUTS

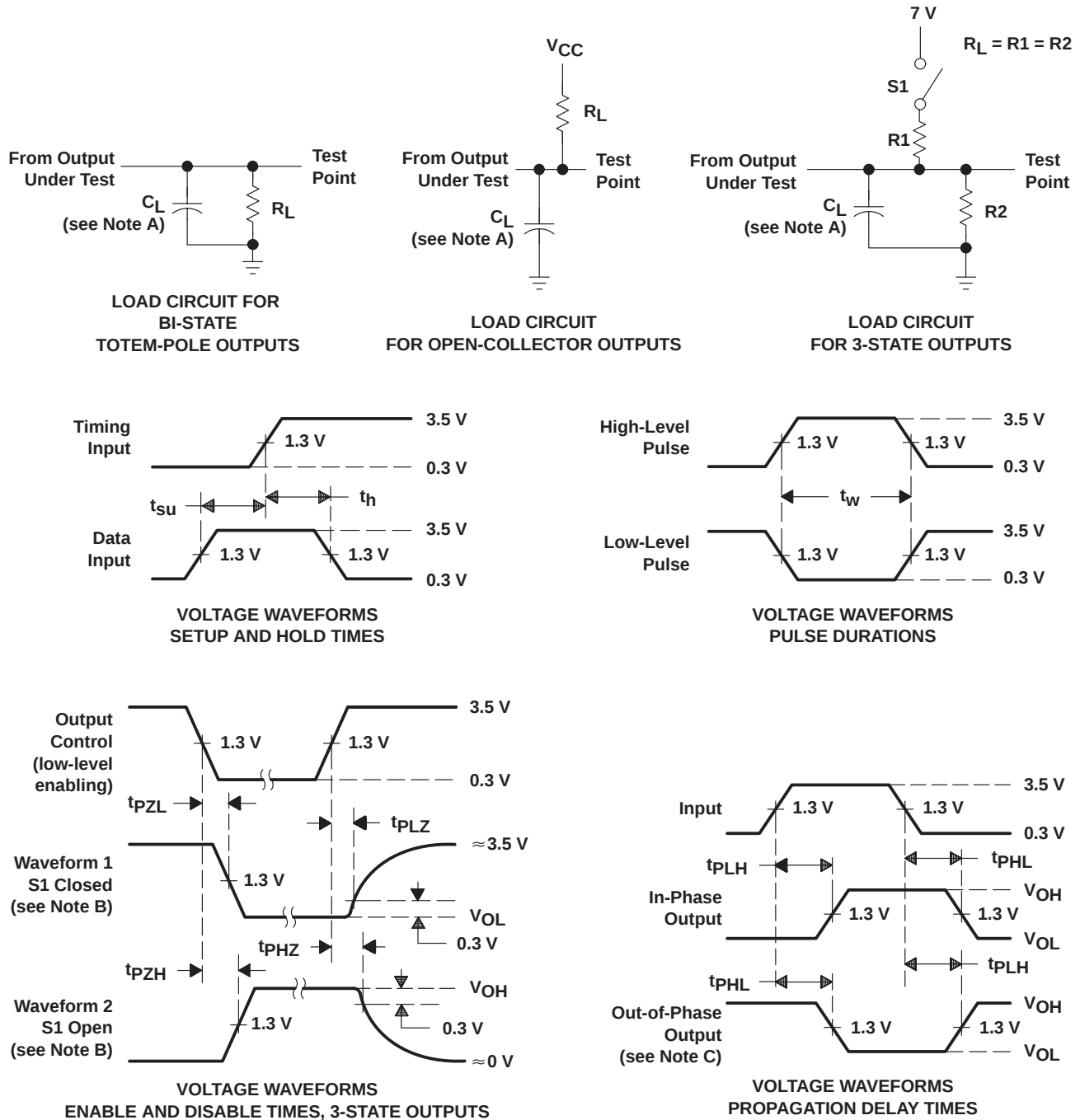
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54AS821A		SN74AS821A		
			MIN	MAX	MIN	MAX	
t _{PLH}	CLK	Any Q	3.5	9	3.5	7.5	ns
t _{PHL}			3.5	14	3.5	13	
t _{PZH}	$\overline{OE}$	Any Q	4	12	3	11	ns
t _{PZL}			4	13	4	12	
t _{PHZ}	$\overline{OE}$	Any Q	1	10	1	8	ns
t _{PLZ}			1	10	1	8	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9078001M3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9078001MKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-9078001MLA	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN54AS821AJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN74AS821ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS821ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS821ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS821ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS821ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS821ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS821ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS821ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54AS821AFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS821AJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AS821AW	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

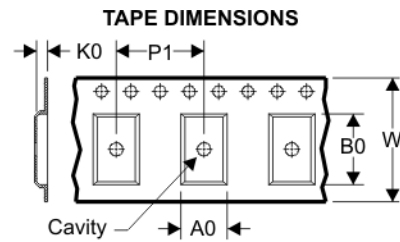
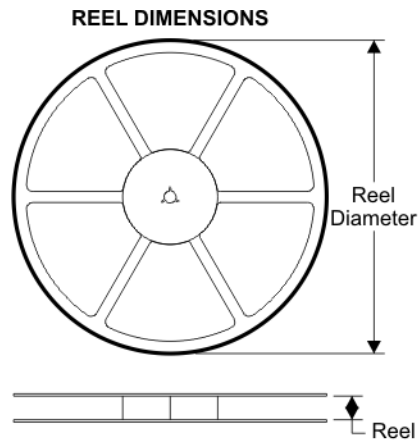
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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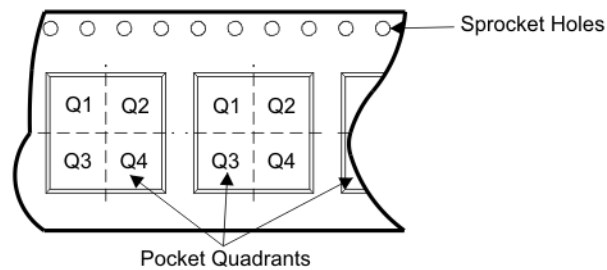
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TAPE AND REEL BOX INFORMATION



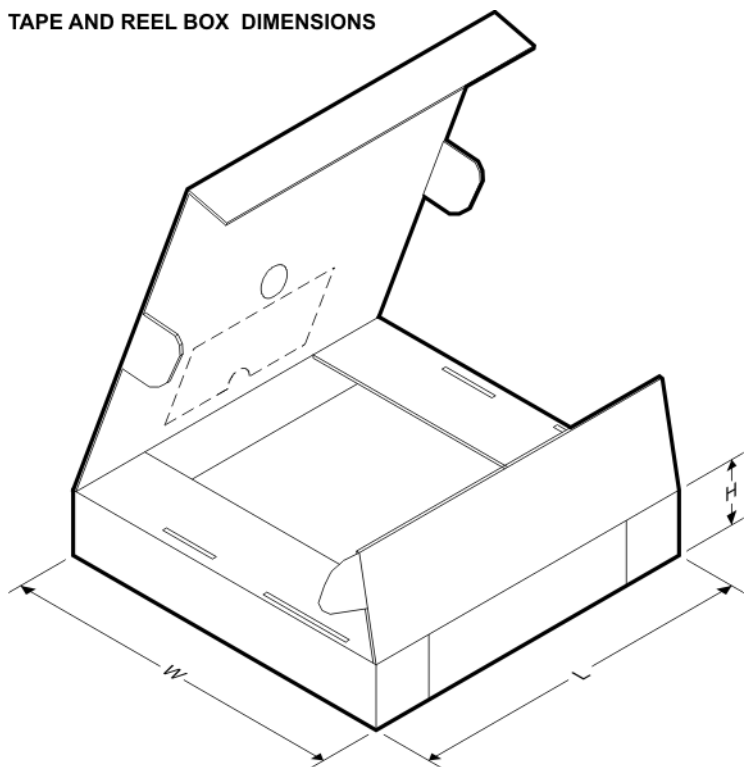
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AS821ADWR	DW	24	SITE 60	330	24	10.75	15.7	2.7	12	24	Q1

TAPE AND REEL BOX DIMENSIONS

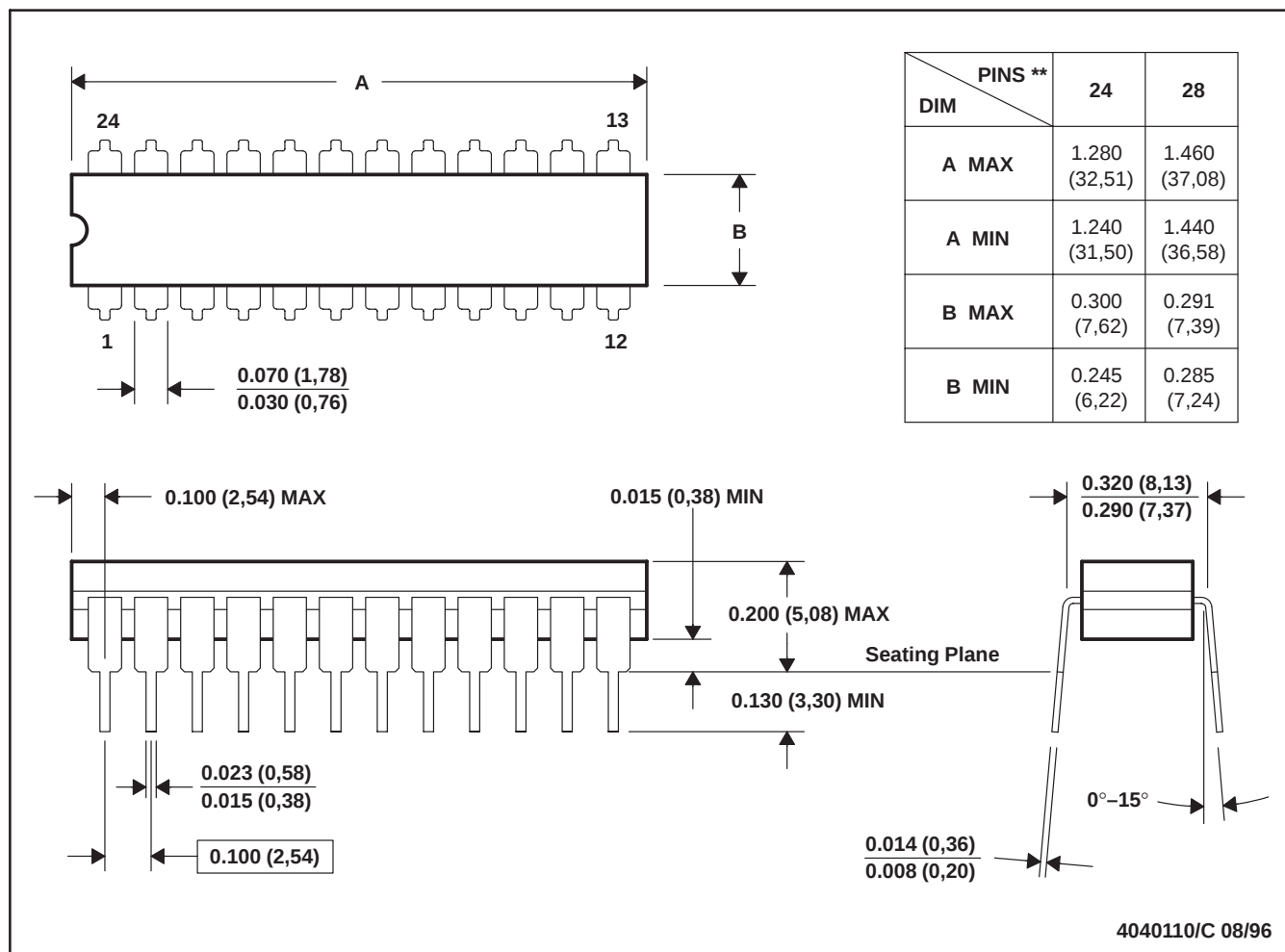


Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AS821ADWR	DW	24	SITE 60	346.0	346.0	0.0

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

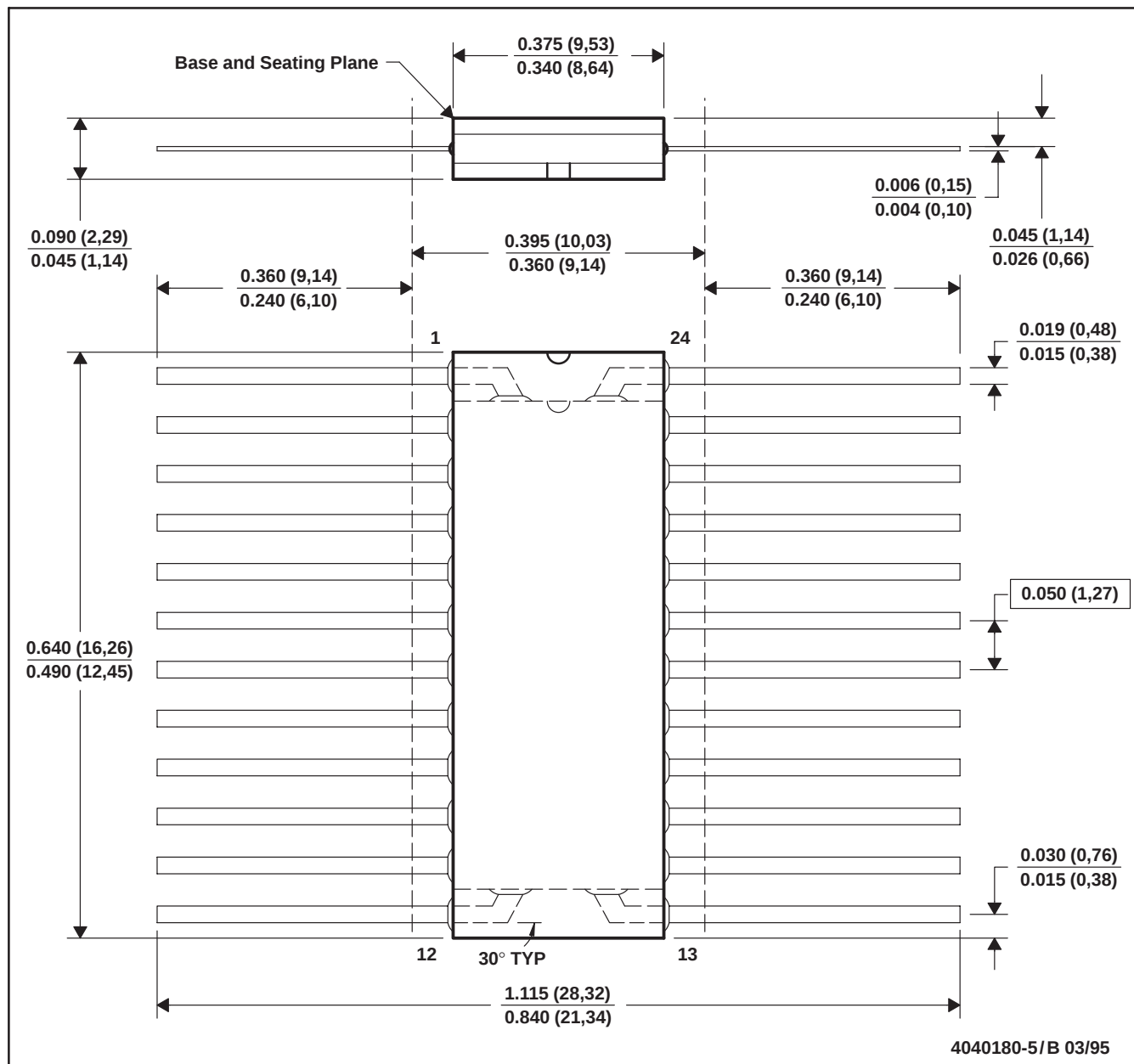
24 LEADS SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification.
 - Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK

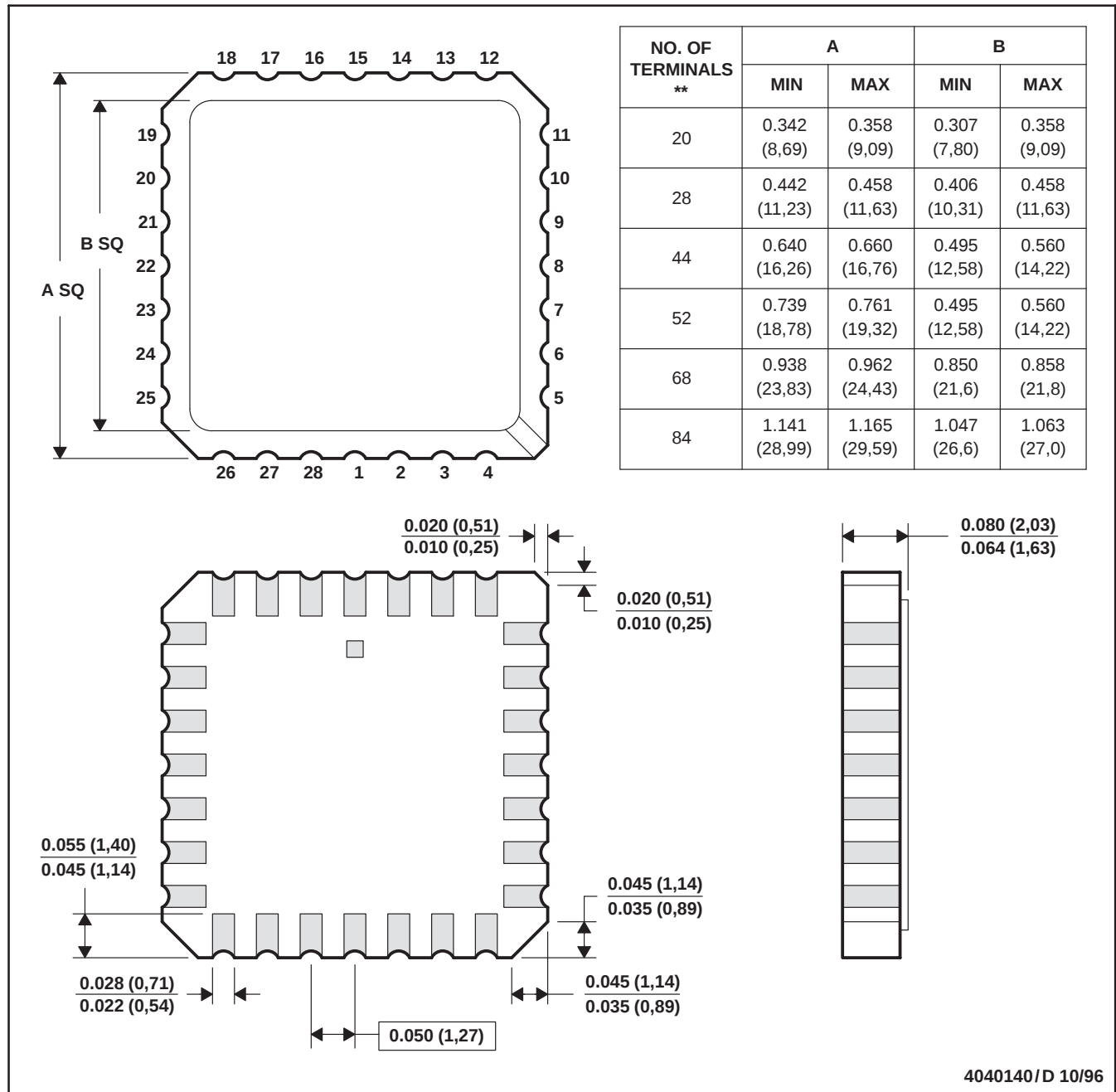


- NOTES:
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 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
 - E. Index point is provided on cap for terminal identification only.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

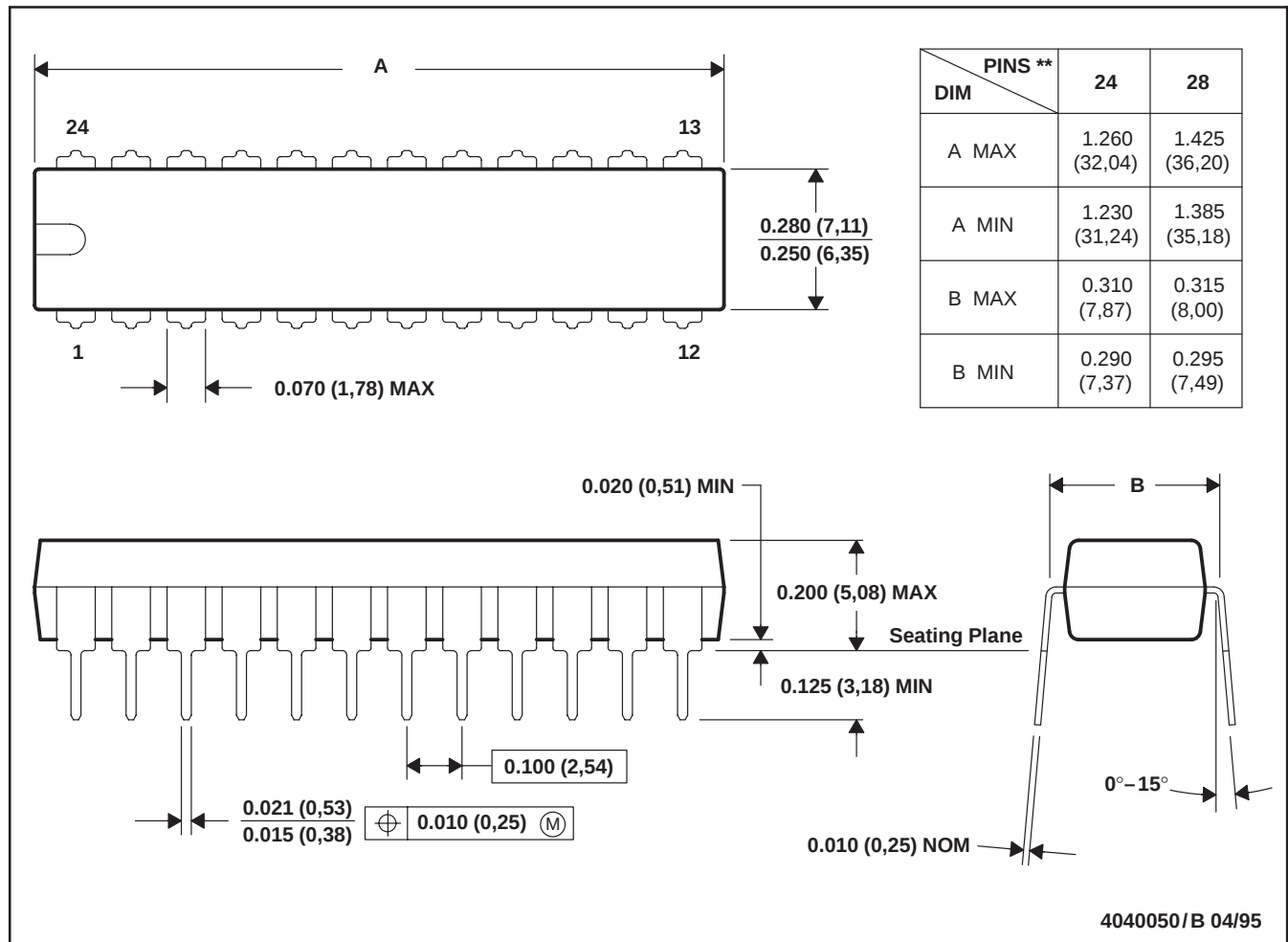


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

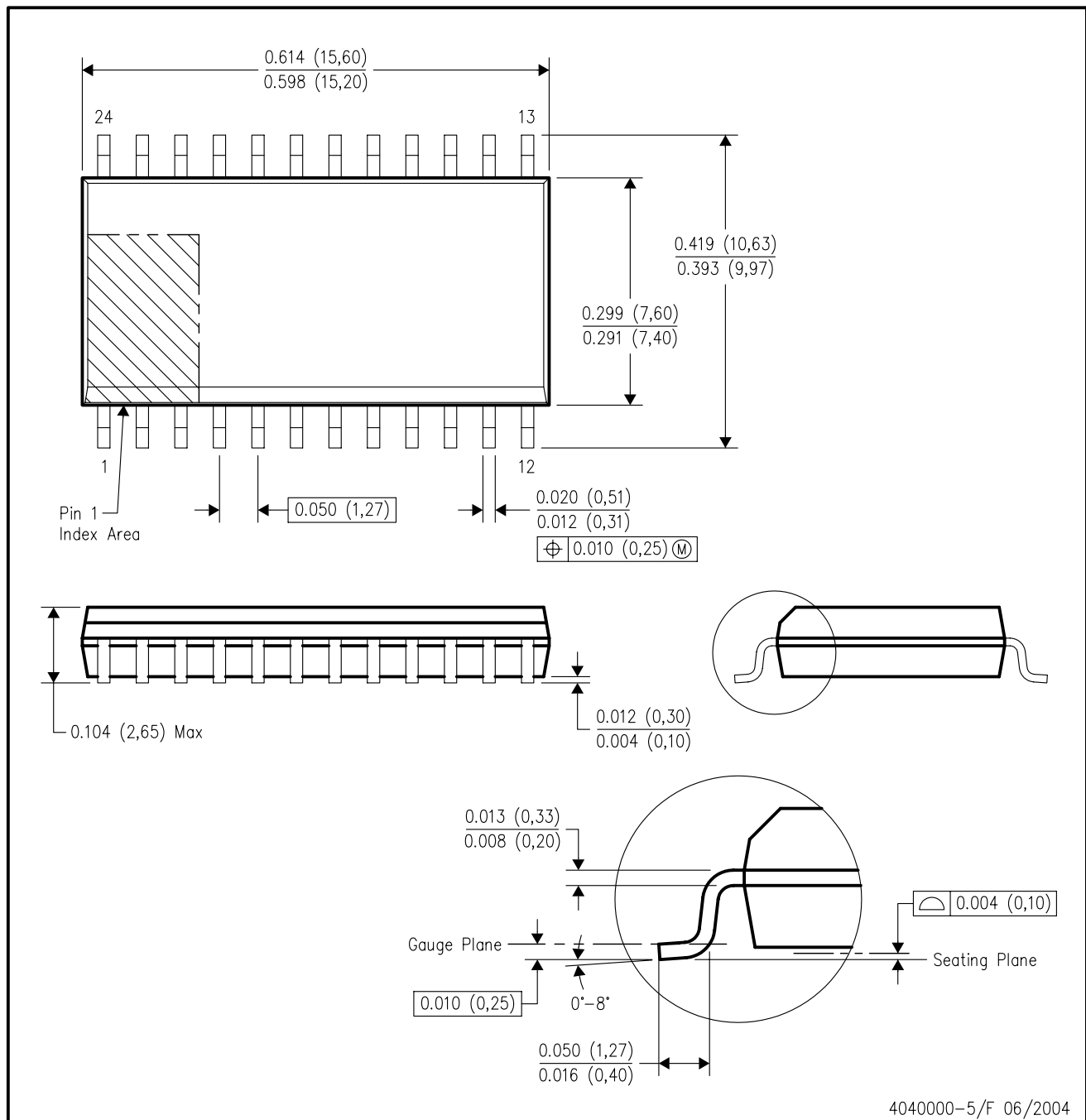
24 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



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